



# IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,  
Assemblies, Related Materials and Processes

For rules and details of the IECQ visit [www.iecq.org](http://www.iecq.org)

## Schedule of Scope to Certificate of Approval

### Independent Testing Laboratory

IECQ Certificate No.: IECQ-L ULTW 16.0003

CB Certificate No.: 20001845 ITL

Schedule Number: IECQ-L ULTW 16.0003-S

Rev No.: 7

Revision Date: 2024/08/29

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## Appendix-1 (20001845 ITL)

### Schedule of Scope to Certificate of Approval

Description test	Standard
Scanning Electron Microscope (SEM)	T-SEM-3
Transmission Electron Microscope - Electron Energy Loss Spectroscopy (TEM-EELS)	T-TEM-3
Energy Dispersive Spectrometry of X-ray (EDS)	T-SEM-3, T-TEM-3
Electron Back Scatter Diffraction (EBSD)	T-TEM-3
Focused Ion Beam microscope (FIB)	T-FIB-3
Liquid Cell Electron Microscopy	T-TEM-3
Secondary Ion Mass Spectrometry (SIMS)	T-SIM-3
Atomic Force Microscope (AFM)	T-SIM-3
Spreading Resistance Probe (SRP)	T-SIM-3
Alpha-step stylus profiler	T-SIM-3
X-Ray Diffraction (XRD)	T-SIM-3
X-Ray Photoelectron Spectroscopy (XPS)	T-SIM-3
X-Ray Fluorescence Spectrometer (XRF)	T-SIM-3

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DQS-Group - DQS Taiwan Inc., Feng Yuan Dist., Taichung City, Taiwan





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X-Ray imaging	T-EFA-3
Emission Microscopy (EMMI)	T-EFA-3
Emission Microscopy (EMMI)-InGaAs	T-EFA-3
Optical Beam Induced Resistance Change (OBIRCH)	T-EFA-3
Conductive atomic force microscopy (C-AFM)	T-EFA-3
Scanning Capacitance Microscopy (SCM)	T-SIM-3
Fourier-Transform Infrared Spectroscopy (FTIR)	T-SIM-3
Nano Probe	T-EFA-3
Scanning Acoustic Tomography (SAT)	T-EFA-3
Optical Microscope (OM)	T-OMI-3
3D Optical Microscope (3D OM)	T-LAB-3
Optical Profiler (OP)	T-SIM-3
IC Layout Imaging	T-OMI-3
Circuitry analysis	T-OMI-3
Auger Electron Spectroscopy (AES)	T-SIM-3
Thermal Emission Microscope (THEMOS)	T-EFA-3
Time Domain Reflectometry (TDR)	T-LAB-3
3D X-Ray microscopy	T-EFA-3

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Latch-up test	JESD78
Human Body Mode (HBM)	ANSI/ESDA/JEDEC JS-001, ANSI/ESD STM 5.1, JESD22-A114, MIL-STD-883, AEC-Q100-002
Machine Mode (MM)	ANSI/ESD S5.2, JESD22-A115, AEC-Q100-003
Charge Device Mode (CDM)	ANSI/ESD SP5.3.2, ANSI/ESD S5.3.1, JESD22-C101, ANSI/ESDA/JEDEC JS-002, AEC-Q100-011,
Electrostatic discharge immunity test	IEC 61000-4-2
Transmission Line Pulse (TLP)	ANSI/ESD STM5.5.1, ANSI/ESD SP5.5.2
Electrical Overstress (EOS)	IEC 61000-4-5
Wire Bonding	T-EFA-3
IC Package	T-EFA-3
Pull and shear test	MIL-STD-883 method 2011.9 MIL-STD-883 method 2023.7 AEC-Q100-001, EIA/JESD22-B116, JESD22-B117
Dynamic Light Scattering (DLS)	B-LAB-3
Thermogravimetric Analyzer (TGA)	B-LAB-3
Differential Scanning Calorimeter (DSC)	B-LAB-3
Inductively Coupled Plasma Mass Spectrometry (ICP-MS)	B-LAB-3
Thin Film Analyzer	T-SIM-3

Technical Reviewer of DQS: \_\_\_\_\_

Date: 8/29/2024

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